F7329



Dual P-Channel 20V (D-S) MOSFET

PRODUCT SUMMARY				
V _{DS} (V)	R _{DS(on)} (Ω)	I _D (A)		
	0.018 at V _{GS} = - 4.5 V	- 8.9		
- 20	0.022 at V _{GS} = - 2.5 V	- 8.1		
	0.030 at V _{GS} = - 1.8 V	- 3.6		

8 D₁

 D_2

7 D₁

6 D₂

5

SO-8

 S_1

G1

S₂ 3

G₂

2

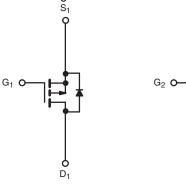
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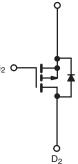


- Halogen-free According to IEC 61249-2-21
 Definition
- TrenchFET[®] Power MOSFET
- Advanced High Cell Density Process
- Compliant to RoHS Directive 2002/95/EC

APPLICATIONS

Load Switching





 S_2

P-Channel MOSFET

P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS $T_A = 25 \degree C$, unless otherwise noted					
Parameter		Symbol	10 s	Steady State	Unit
Drain-Source Voltage		V _{DS}	- 20		V
Gate-Source Voltage		V _{GS}	± 12		
Continuous Drain Current (T _J = 150 °C) ^a	T _A = 25 °C	1	- 8.9	- 6.7	
	T _A = 70 °C	D ID	- 7.1	- 5.4	
Pulsed Drain Current		I _{DM}	- 30		A
Continuous Source Current (Diode Conduction) ^a		۱ _S	- 1.7	- 0.9	
	T _A = 25 °C	Р	2.0 1.1		14/
Maximum Power Dissipation ^a	T _A = 70 °C	P _D	1.3	0.7	W
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150		°C

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
	t ≤ 10 s	R _{thJA}	46	62.5	°C/W
Maximum Junction-to-Ambient ^a	Steady State		80	110	
Maximum Junction-to-Foot (Drain)	Steady State	R _{thJF}	24	32	

Notes:

a. Surface Mounted on 1" x 1" FR4 board.

HALOGEN

FREE

SPECIFICATIONS $T_J = 25 \text{ °C}$, unless otherwise noted								
Parameter Sym		Test Conditions	Min.	Тур.	Max.	Unit		
Static								
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = -350 \ \mu A$	- 0.4		- 1.0	V		
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 8 V$			± 100	nA		
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = -20 V, V_{GS} = 0 V$			- 1	μA		
Zero Gale voltage Drain Current	USS	V_{DS} = - 20 V, V_{GS} = 0 V, T_{J} = 55 °C			- 5	μΛ		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} = -5 V, V_{GS} = -4.5 V$	- 30			А		
		V _{GS} = - 4.5 V, I _D = - 8.9 A		0.018				
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = - 2.5 V, I _D = - 8.1 A		0.022		Ω		
		V _{GS} = - 1.8 V, I _D = - 3.6 A 0.030						
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 10 V, I _D = - 8.9 A		26		S		
Diode Forward Voltage ^a	V _{SD}	I _S = - 1.7 A, V _{GS} = 0 V		- 0.7	- 1.2	V		
Dynamic ^b								
Total Gate Charge	Qg			34.5	52			
Gate-Source Charge	Q _{gs}	V_{DS} = - 10 V, V_{GS} = - 4.5 V, I_D = - 8.9 A		5.1		nC		
Gate-Drain Charge	Q _{gd}			9.6				
Gate Resistance	Rg			9		Ω		
Turn-On Delay Time	t _{d(on)}			25	40			
Rise Time	t _r	V_{DD} = - 10 V, R_L = 6 Ω		46	70			
Turn-Off Delay Time t _{d(off)} Fall Time t _f		$\text{I}_\text{D}\cong$ - 1 A, V_GEN = - 4.5 V, R_g = 6 Ω		230	345	ns		
				155	235			
Source-Drain Reverse Recovery Time	t _{rr}	I _F = - 1.7 A, dl/dt = 100 A/μs		128	200			

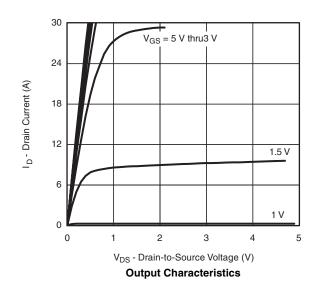
Notes:

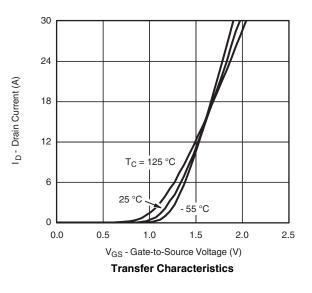
a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %.

b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

TYPICAL CHARACTERISTICS 25 °C unless otherwise noted





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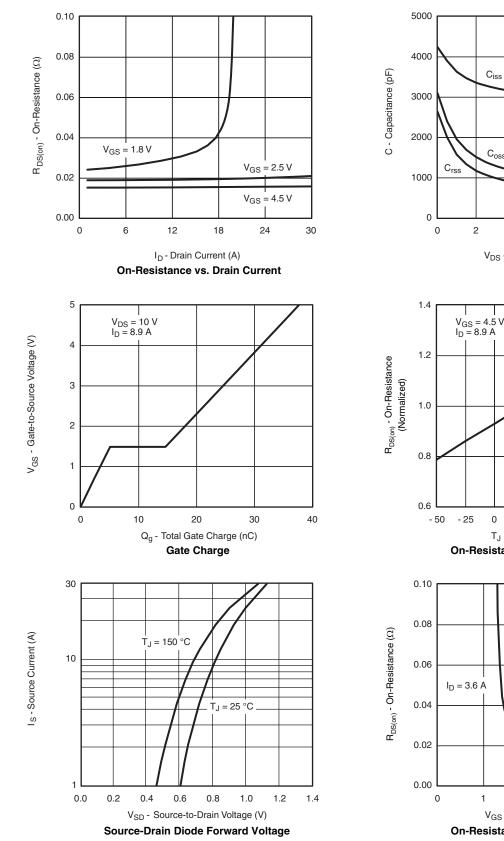


Ciss

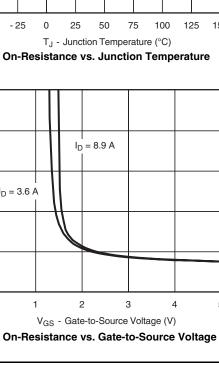
 C_{oss}

V_{DS} - Drain-to-Source Voltage (V)

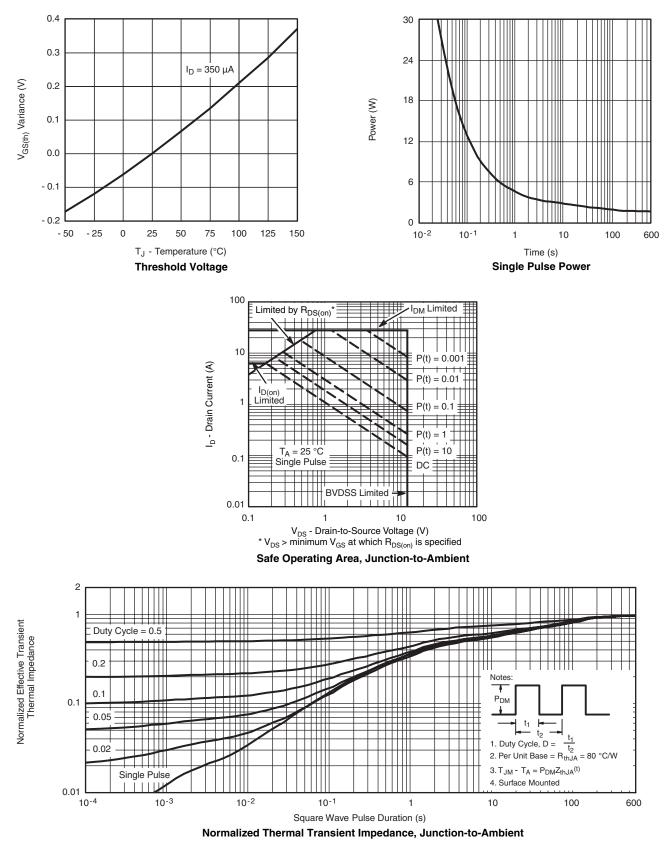
Capacitance



TYPICAL CHARACTERISTICS 25 °C unless otherwise noted

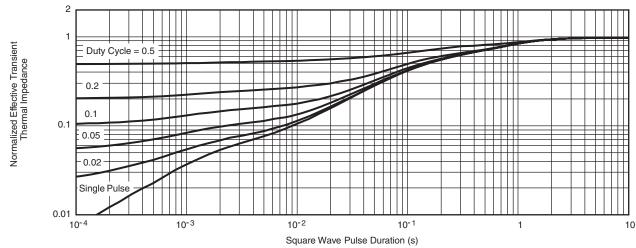




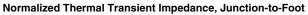


TYPICAL CHARACTERISTICS 25 °C unless otherwise noted



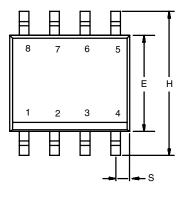


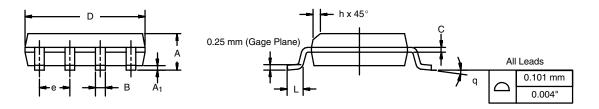
TYPICAL CHARACTERISTICS 25 °C unless otherwise noted





SOIC (NARROW): 8-LEAD JEDEC Part Number: MS-012

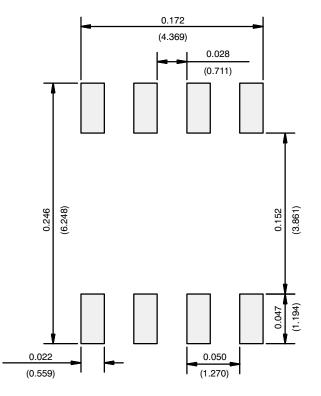




	MILLIM	IETERS	INC	HES	
DIM	Min	Мах	Min	Max	
A	1.35	1.75	0.053	0.069	
A ₁	0.10	0.20	0.004	0.008	
В	0.35	0.51	0.014	0.020	
С	0.19	0.25	0.0075	0.010	
D	4.80	5.00	0.189	0.196	
E	3.80	4.00	0.150	0.157	
е	1.27	BSC	0.050 BSC		
н	5.80	6.20	0.228	0.244	
h	0.25	0.50	0.010	0.020	
L	0.50	0.93	0.020	0.037	
q	0°	8°	0°	8°	
S	0.44	0.64	0.018	0.026	
ECN: C-06527-Rev. I, 11-Sep-06 DWG: 5498					



RECOMMENDED MINIMUM PADS FOR SO-8



Recommended Minimum Pads Dimensions in Inches/(mm)

Return to Index



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